Function Table[1]

Inputs			Outputs
$\overline{OE}$	LE	D	O
L	H	H	H
L	H	L	L
L	L	X	Q_0
H	X	X	Z

Maximum Ratings[2, 3]

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature ..... −65°C to +150°C

Ambient Temperature with Power Applied ..... −65°C to +135°C

Supply Voltage to Ground Potential ..... −0.5V to +7.0V

DC Input Voltage ..... −0.5V to +7.0V

DC Output Voltage ..... −0.5V to +7.0V

DC Output Current (Maximum Sink Current/Pin) .... 120 mA

Power Dissipation 0.5W

Static Discharge Voltage ..... >2001V (per MIL-STD-883, Method 3015)

Operating Range

Range	Range	Ambient Temperature	V_{CC}
Commercial	CT, DT	0°C to +70°C	5V ± 5%
Commercial	T, AT	−40°C to +85°C	5V ± 5%
Military[4]	All	−55°C to +125°C	5V ± 10%

Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions		Min.	Typ.[5]	Max.	Unit
V_{OH}	Output HIGH Voltage	V_{CC}=Min., I_{OH}=−15 mA	Com'l	2.4	3.3		V
		V_{CC}=Min., I_{OH}=−12 mA	Mil	2.4	3.3		V
V_{OL}	Output LOW Voltage	V_{CC}=Min., I_{OL}=12 mA	Com'l		0.3	0.55	V
		V_{CC}=Min., I_{OL}=12 mA	Mil		0.3	0.55	V
R_{OUT}	Output Resistance	V_{CC}=Min., I_{OL}=12 mA	Com'l	20	28	40	Ω
		V_{CC}=Min., I_{OL}=12 mA	Mil		25		Ω
V_{IH}	Input HIGH Voltage			2.0			V
V_{IL}	Input LOW Voltage					0.8	V
V_H	Hysteresis[6]	All inputs			0.2		V
V_{IK}	Input Clamp Diode Voltage	V_{CC}=Min., I_{IN}=−18 mA			−0.7	−1.2	V
I_I	Input HIGH Current	V_{CC}=Max., V_{IN}=V_{CC}				5	µA
I_{IH}	Input HIGH Current	V_{CC}=Max., V_{IN}=2.7V				±1	µA
I_{IL}	Input LOW Current	V_{CC}=Max., V_{IN}=0.5V				±1	µA
I_{OZH}	Off State HIGH-Level Output Current	V_{CC} = Max., V_{OUT} = 2.7V				10	µA
I_{OZL}	Off State LOW-Level Output Current	V_{CC} = Max., V_{OUT} = 0.5V				−10	µA
I_{OS}	Output Short Circuit Current[7]	V_{CC}=Max., V_{OUT}=0.0V		−60	−120	−225	mA
I_{OFF}	Power-Off Disable	V_{CC}=0V, V_{OUT}=4.5V				±1	µA

Notes:

1. H = HIGH Voltage Level
   L = LOW Voltage Level
   X = Don't Care
   Z = HIGH Impedance
   Q_n = Previous state of flip-flops (Q_{n-1})
2. Unless otherwise noted, these limits are over the operating free-air temperature range.
3. Unused inputs must always be connected to an appropriate logic voltage level, preferably either V_{CC} or ground.
4. T_A is the "instant on" case temperature.
5. Typical values are at V_{CC}=5.0V, T_A=+25°C ambient.
6. This parameter is guaranteed but not tested.
7. Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample and hold techniques are preferable in order to minimize internal chip heating and more accurately reflect operational values. Otherwise prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parametric tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

Capacitance[6]

Parameter	Description	Typ.[5]	Max.	Unit
C_{IN}	Input Capacitance	6	10	pF
C_{OUT}	Output Capacitance	8	12	pF

Power Supply Characteristics

Parameter	Description	Test Conditions	Typ.[5]	Max.	Unit
I_{CC}	Quiescent Power Supply Current	V_{CC}=Max., $V_{IN} \le 0.2V$, $V_{IN} \ge V_{CC}-0.2V$	0.1	0.2	mA
ΔI_{CC}	Quiescent Power Supply Current (TTL inputs)	V_{CC}=Max., V_{IN}=3.4V,[8] f_1=0, Outputs Open	0.5	2.0	mA
I_{CCD}	Dynamic Power Supply Current[9]	V_{CC}=Max., One Input Toggling, 50% Duty Cycle, Outputs Open, $\overline{OE}$=GND, $V_{IN} \le 0.2V$ or $V_{IN} \ge V_{CC}-0.2V$	0.06	0.12	mA/ MHz
I_C	Total Power Supply Current[10]	V_{CC}=Max., 50% Duty Cycle, Outputs Open, One Bit Toggling at f_1=10 MHz, $\overline{OE}$=GND, LE=V_{CC}, $V_{IN} \le 0.2V$ or $V_{IN} \ge V_{CC}-0.2V$	0.7	1.4	mA
		V_{CC}=Max., 50% Duty Cycle, Outputs Open, One Bit Toggling at f_1=10 MHz, $\overline{OE}$=GND, LE=V_{CC}, V_{IN}=3.4V or V_{IN}=GND	1.0	2.4	mA
		V_{CC}=Max., 50% Duty Cycle, Outputs Open, Eight Bits Toggling at f_1=2.5 MHz, $\overline{OE}$=GND, LE=V_{CC}, $V_{IN} \le 0.2V$ or $V_{IN} \ge V_{CC}-0.2V$	1.3	2.6[11]	mA
		V_{CC}=Max., 50% Duty Cycle, Outputs Open, Eight Bits Toggling at f_1=2.5 MHz, $\overline{OE}$=GND, LE=V_{CC}, V_{IN}=3.4V or V_{IN}=GND	3.3	10.6[11]	mA

Notes:

8. Per TTL driven input (V_{IN}=3.4V); all other inputs at V_{CC} or GND.
9. This parameter is not directly testable, but is derived for use in Total Power Supply calculations.
10. $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$
    $I_C = I_{CC}+\Delta I_{CC}D_HN_T+I_{CCD}(f_0/2 + f_1N_1)$
    I_{CC} = Quiescent Current with CMOS input levels
    ΔI_{CC} = Power Supply Current for a TTL HIGH input (V_{IN}=3.4V)
    D_H = Duty Cycle for TTL inputs HIGH
    N_T = Number of TTL inputs at D_H
    I_{CCD} = Dynamic Current caused by an input transition pair (HLH or LHL)
    f_0 = Clock frequency for registered devices, otherwise zero
    f_1 = Input signal frequency
    N_1 = Number of inputs changing at f_1
    All currents are in milliamps and all frequencies are in megahertz.
11. Values for these conditions are examples of the I_{CC} formula. These limits are guaranteed but not tested.

Switching Characteristics Over the Operating Range

Parameter	Description	FCT2373T/FCT2573T				FCT2373AT/FCT2573AT				Unit	Fig. No.[13]
		Military		Commercial		Military		Commercial			
		Min.[12]	Max.	Min.[12]	Max.	Min.[12]	Max.	Min.[12]	Max.		
t_{PLH} t_{PHL}	Propagation Delay D to O	1.5	8.5	1.5	8.0	1.5	5.6	1.5	5.2	ns	1, 3
t_{PLH} t_{PHL}	Propagation Delay LE to O	2.0	14.0	2.0	13.0	2.0	9.8	2.0	8.5	ns	1, 5
t_{PZH} t_{PZL}	Output Enable Time	1.5	12.5	1.5	11.0	1.5	7.5	1.5	6.5	ns	1, 7, 8
t_{PHZ} t_{PLZ}	Output Disable Time	1.5	8.5	1.5	7.0	1.5	6.5	1.5	5.5	ns	1, 7, 8
t_S	Set-Up Time, HIGH to LOW D to LE	2.0		2.0		2.0		2.0		ns	9
t_H	Hold Time, HIGH to LOW D to LE	1.5		1.5		1.5		1.5		ns	9
t_W	LE Pulse Width HIGH	6.0		6.0		6.0		5.0		ns	5

Parameter	Description	FCT2373CT/FCT2573CT				FCT2373DT/ FCT2573DT		Unit	Fig. No.[13]
		Military		Commercial		Commercial			
		Min.[12]	Max.	Min.[12]	Max.	Min.[12]	Max.		
t_{PLH} t_{PHL}	Propagation Delay D to O	1.5	5.1	1.5	4.2	1.5	3.8	ns	1, 3
t_{PLH} t_{PHL}	Propagation Delay LE to O	2.0	8.0	2.0	5.5	2.0	4.0	ns	1, 5
t_{PZH} t_{PZL}	Output Enable Time	1.5	6.3	1.5	5.5	1.5	4.8	ns	1, 7, 8
t_{PHZ} t_{PLZ}	Output Disable Time	1.5	5.9	1.5	5.0	1.5	4.0	ns	1, 7, 8
t_S	Set-Up Time, HIGH to LOW, D to LE	2.0		2.0		1.5		ns	9
t_H	Hold Time, HIGH to LOW, D to LE	1.5		1.5		1.0		ns	9
t_W	LE Pulse Width HIGH	6.0		5.0		3.0		ns	5

Shaded areas contain preliminary information.

Notes:

12. Minimum limits are guaranteed but not tested on Propagation Delays.
13. See "Parameter Measurement Information" in the General Information Section.

Ordering Information

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
3.8	CY74FCT2373DTQC	Q5	20-Lead (150-Mil) QSOP	Commercial
	CY74FCT2373DTSOC	S5	20-Lead (300-Mil) Molded SOIC	
4.2	CY74FCT2373CTPC	P5	20-Lead (300-Mil) Molded DIP	Commercial
	CY74FCT2373CTQC	Q5	20-Lead (150-Mil) QSOP	
	CY74FCT2373CTSOC	S5	20-Lead (300-Mil) Molded SOIC	
5.1	CY54FCT2373CTDMB	D6	20-Lead (300-Mil) CerDIP	Military
	CY54FCT2373CTLMB	L61	20-Pin Square Leadless Chip Carrier	
5.2	CY74FCT2373ATPC	P5	20-Lead (300-Mil) Molded DIP	Commercial
	CY74FCT2373ATQC	Q5	20-Lead (150-Mil) QSOP	
	CY74FCT2373ATSOC	S5	20-Lead (300-Mil) Molded SOIC	
5.6	CY54FCT2373ATDMB	D6	20-Lead (300-Mil) CerDIP	Military
	CY54FCT2373ATLMB	L61	20-Pin Square Leadless Chip Carrier	
8.0	CY74FCT2373TPC	P5	20-Lead (300-Mil) Molded DIP	Commercial
	CY74FCT2373TQC	Q5	20-Lead (150-Mil) QSOP	
	CY74FCT2373TSOC	S5	20-Lead (300-Mil) Molded SOIC	
8.5	CY54FCT2373TDMB	D6	20-Lead (300-Mil) CerDIP	Military
	CY54FCT2373TLMB	L61	20-Pin Square Leadless Chip Carrier	

Ordering Information

Speed (ns)	Ordering Code	Package Name	Package Type	Operating Range
3.8	CY74FCT2573DTQC	Q5	20-Lead (150-Mil) QSOP	Commercial
	CY74FCT2573DTSOC	S5	20-Lead (300-Mil) Molded SOIC	
4.2	CY74FCT2573CTPC	P5	20-Lead (300-Mil) Molded DIP	Commercial
	CY74FCT2573CTQC	Q5	20-Lead (150-Mil) QSOP	
	CY74FCT2573CTSOC	S5	20-Lead (300-Mil) Molded SOIC	
5.1	CY54FCT2573CTDMB	D6	20-Lead (300-Mil) CerDIP	Military
	CY54FCT2573CTLMB	L61	20-Pin Square Leadless Chip Carrier	
5.2	CY74FCT2573ATPC	P5	20-Lead (300-Mil) Molded DIP	Commercial
	CY74FCT2573ATQC	Q5	20-Lead (150-Mil) QSOP	
	CY74FCT2573ATSOC	S5	20-Lead (300-Mil) Molded SOIC	
5.6	CY54FCT2573ATDMB	D6	20-Lead (300-Mil) CerDIP	Military
	CY54FCT2573ATLMB	L61	20-Pin Square Leadless Chip Carrier	
8.0	CY74FCT2573TPC	P5	20-Lead (300-Mil) Molded DIP	Commercial
	CY74FCT2573TQC	Q5	20-Lead (150-Mil) QSOP	
	CY74FCT2573TSOC	S5	20-Lead (300-Mil) Molded SOIC	
8.5	CY54FCT2573TDMB	D6	20-Lead (300-Mil) CerDIP	Military
	CY54FCT2573TLMB	L61	20-Pin Square Leadless Chip Carrier	

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Document #: 38-00338-A